



## Material Content Data Sheet



<b>Sales Product Name</b>	TLE7469G V53			<b>Issued</b>	25. September 2017			
<b>MA#</b>	MA001264324							
<b>Package</b>	PG-DSO-12-11			<b>Weight*</b>	401.93 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.559	0.89	0.89	8854	8854
leadframe	non noble metal	iron	7439-89-6	0.230	0.06		573	
	inorganic material	phosphorus	7723-14-0	0.069	0.02		172	
	non noble metal	copper	7440-50-8	230.106	57.24	57.32	572497	573242
wire	non noble metal	aluminium	7429-90-5	0.155	0.04	0.04	386	386
encapsulation	organic material	carbon black	1333-86-4	0.316	0.08		787	
	plastics	epoxy resin	-	14.549	3.62		36196	
	inorganic material	silicondioxide	60676-86-0	143.272	35.65	39.35	356456	393439
leadfinish	non noble metal	tin	7440-31-5	4.235	1.05	1.05	10537	10537
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		3	
	non noble metal	nickel	7440-02-0	0.537	0.13	0.13	1336	1339
solder	noble metal	silver	7440-22-4	0.123	0.03		305	
	non noble metal	tin	7440-31-5	0.098	0.02		244	
	non noble metal	lead	7439-92-1	4.684	1.17	1.22	11654	12203
*deviation	< 10%			Sum in total:		100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com